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(21) International Application Number: PCT/US96/09838 ✓ (22) International Filing Date: 7 June 1996 (07.06.96) ✓ (30) Priority Data: 08/488,469 7 June 1995 (07.06.95) ✓ US (71) Applicant: THE DEXTER CORPORATION [US/US]; 2850 Willow Pass Road, Pittsburg, CA 94565 (US). ✓ (72) Inventors: GEBHARDT, William, F.; 639 Odin Drive, Pleasant Hill, CA 94523 (US). PAPALIA, Rocco; 3331 Blue Jay Drive, Antioch, CA 94509 (US). (74) Agents: BRUHN, David, E. et al.; Dorsey & Whitney L.L.P., Pillsbury Center South, 220 South Sixth Street, Minneapolis, MN 55402 (US).	(81) Designated States: AL, AM, AT, AU, AZ, BB, BG, BR, BY, CA, CH, CN, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IS, JP, KE, KG, KP, KR, KZ, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TR, TT, UA, UG, UZ, VN, ARIPO patent (KE, LS, MW, SD, SZ, UG), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>	
(54) Title: DEBOSSABLE FILMS (57) Abstract A thin thermosetting resin film that is amenable to being subjected to a debossing procedure that debosses a grooved printed circuit pattern thereon with minimal loss of debossment precision of the grooved pattern, which pattern and the grooving can be cured to produce a thermoset resin film that can be employed for eventually generating a printed board. The thermosetting film can be shaped without the need for constraining flow at the edges of the resin film. The resin is nonconductive and the film is sufficiently uniform in thickness in order to provide consistent heat shaping capability across the breadth of the film. The film possesses low flow over a broad temperature range so that it does not flow uncontrollably while undergoing cure conditions. The film gels or achieves properties similar to a state of gelation, over conditions leading to cure, that satisfy commercial conditions.		